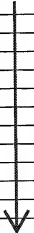




Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. <b>292873US41PCT</b>		SERIAL NO. <b>10/584,052</b>		
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT <b>Stephane POCAS, et al.</b>				
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		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO			
		AO 2 783 969	03/31/00	France (equivalent of US 6, 281, 039)			X	
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		AW	Q.-Y TONG, et al., "SEMICONDUCTOR WAFER BONDING: SCIENCE AND TECHNOLOGY", JOHN WILEY & SONS, INC., XP 008042464, pages 215-219, 1999.					
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	BZ					<input type="checkbox"/> Additional References sheet(s) attached	
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*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							